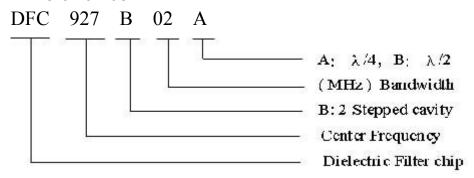
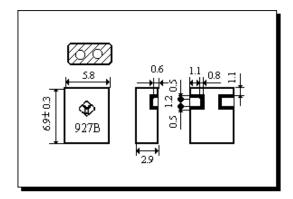
INTRODUTION

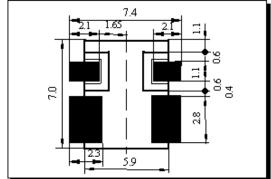
Microwave Dielectric filter series are designed to be used in mobile & cordless phones with low insertion loss and high attenuation as well as chip design, which can simplify your complex tunning and circuit design.

Part Number



Dimension Unit mm





Structure and Material

Table 1

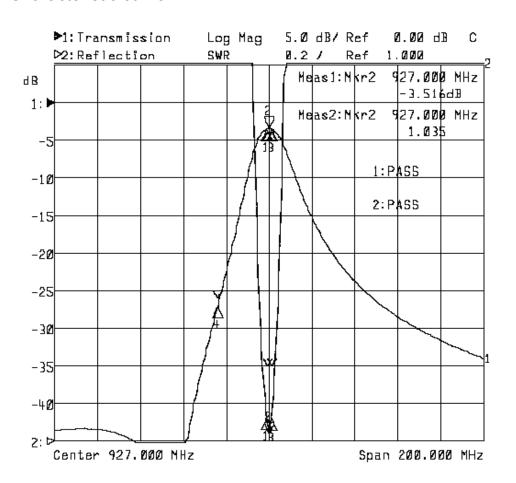
NO	Part Name	Structure and material	
4.1	Filter	Dielectric material	
4.2	Number of pole	2 pole	
4.3	In/output Terminals	Ag Plated	
4.4	Ground Base	Ag Plated	

Electrical Characteristics

Table 2

NO	Item	Specifications	Post Environmental Tolerance
5.1	Center frequency (fo)	927.00 MHz	-/+1.5MHz
5.2	Insertion loss	4.0 dB	-/+0.5 dB
5.3	Band width	fo-/+1.0MHz	-/+0.5 MHz
5.4	Ripple (in BW)	0.5 dB Max.	-/+0.5 dB
5.5	V.S.W.R (in BW)	2.0 Max.	-/+0.5
5.6	Attenuation (Absolute value)	23 (in 903MHz)	-/+2 dB
5.7	Permissible Input power (Max)	1 Watt	
5.8	In/output impedance	50	

Characteristic curve



Environmental specifications

Post Environmental Tolerance (Refer to the table 2)

Temperature range 25–/+3 °C Relative Humidity range 55~75%RH Operating Temperature range Storage Temperature range -10 °C ~+70 °C -25 °C ~+85 °C

Moisture Proof

The device should satisfy the electrical characteristics specified in paragraph $5.1\sim5.6$ after exposed to the temperature 40–/+2 °C and the relative humidity $90\sim95\%$ RH for 96 hours and $1\sim2$ hours recovery time under normal condition.

Vibration Resist

The device should satisfy the electrical characteristics specified in paragraph $5.1\sim5.6$ after applied to the vibration of 10 to 55Hz with amplitude of 1.5mm for 2 hours each in X, Y and Z directions.

Drop Shock

The device should satisfy the electrical characteristics specified in paragraph 5.1~5.6 after dropping onto the hard wooden board from the height of 30cm for 3 times each facet of the 3 dimensions of the device.

High Temperature Endurance

The device should satisfy the electrical characteristics specified in paragraph $5.1\sim5.6$ after exposed to temperature 80–/+5 °C for 24–/+2 hours and $1\sim2$ hours recovery time under normal temperature.

Low Temperature Endurance

The device should also satisfy the electrical characteristics specified in paragraph 5.1~5.6 after exposed to the temperature -25 °C-/+3 °C for 24-/+2 hours and to 2 hours recovery time under normal temperature.

Temperature Cycle Test

The device should also satisfy the electrical characteractics specified in paragraph $5.1\sim5.6$ after exposed to the low temperature -25 °C and high temperature +85 °C for 30–/+2 min each by 5 cycles and 1 to 2 hours recovery time under normal temperature.



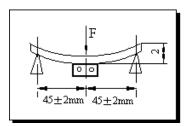
Solder Heat Proof

The device should be satisfied after preheating at $120\,^{\circ}$ C $\sim 150\,^{\circ}$ C for 60 seconds and dipping in soldering Sn at $260\,^{\circ}$ C $+10\,^{\circ}$ C for 10-/+0.5 seconds.

Tensile Strength of Terminal

The device should not be broken after tensile force of 1.0kg is slowly applied to pull a lead pin of the fixed device in the lead axis direction for 10-/+1 seconds.

Bending Resist Test



Weld the product to the center part of the PCB with the thickness 1.6–/+0.2mm as the illustration shows, and keep exerting force arrow-ward on it at speed of : 1mm/S , and hold for 5–/+1S at the position of 2mm bending distance , so far , any peeling off of the product metal coating should not be detected .

Reflow Soldering Standard Condision

